

## Application Data Sheet

### Application Information

Application Type:: Regular  
Subject Matter:: Utility  
Title:: Die Bonding Apparatus With Automatic  
Die And Lead Frame Image Matching System  
Attorney Docket Numer:: IDT-1661  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure:: 4  
Total Drawing Sheets:: 3  
Small Entity:: No  
Petition included?:: No  
Secrecy Order in Parent Appl.?:: No

### Inventor Information

Inventor Authority type:: Inventor  
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### Representative Information

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**Foreign Priority Information**

Country::	Application Number::	Filing Date::
Malaysia	PI 20012544	05/29/01

**Assignee Information**

Assignee Name:: Integrated Device Technology, Inc.